



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-03-07
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Laurent TOSI	Representative Title	MMS MD CHAMPION
Representative Phone *	33 442 685 795	Representative Email *	laurent.tosi@st.com
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement


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Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32L152ZET6	S01A*437XXXA	A	9994	2014-03-07
	Amount	UoM	Unit type	ST ECOPACK Grade
	1315.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	20x20x1.4	144	L bend	
Comment	Package: LQFP 144 20X20X1.4 2			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	S01A*437XXXA					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	19.132	mg	supplier	die	Silicon (Si)	7440-21-3		18.508	mg	967384	14075
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.051	mg	2666	39
die (s)				supplier	metallization	Copper (Cu)	7440-50-8		0.222	mg	11604	169
die (s)				supplier	metallization	Tantalum (Ta)	7440-25-7		0.006	mg	314	5
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0.024	mg	1254	18
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	52	1
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.045	mg	2352	34
die (s)				supplier	passivation	Indium Tin oxide (In2O3·SnO2)	50926-11-9		0.275	mg	14374	209
Die Attach	Other inorganic materials	3.240	mg	supplier	Glue	Acrylic resins	Trade secret		0.486	mg	150000	370
Die Attach				supplier	Glue	Resin	Trade secret		0.081	mg	25000	62
Die Attach				supplier	Glue	Silver (Ag)	7440-22-4		2.592	mg	800000	1971
Die Attach				supplier	Glue	Treated silica	96-48-0		0.081	mg	25000	62
Leadframe	Other inorganic materials	256.179	mg	supplier	Alloy	Copper (Cu)	7440-50-8		240.737	mg	939722	183070
Leadframe				supplier	Alloy	Iron (Fe)	7439-89-6		5.802	mg	22648	4412
Leadframe				supplier	Alloy	Phosphorous (P)	7723-14-0		0.074	mg	289	56
Leadframe				supplier	Alloy	Zinc (Zn)	7440-66-6		0.296	mg	1155	225
Leadframe				supplier	Coating	Nickel (Ni)	7440-02-0		9.042	mg	35296	6876
Leadframe				supplier	Coating	Palladium (Pd)	7440-05-3		0.192	mg	749	146
Leadframe				supplier	Coating	Gold(Au)	7440-57-5		0.020	mg	78	15
Leadframe				supplier	Coating	Silver(Ag)	7440-22-4		0.016	mg	62	12
Encapsulation	Other inorganic materials	1032.846	mg	supplier	Mold compound	Epoxy Resin (Proprietary)	Proprietary		31.004	mg	30018	23577
Encapsulation				supplier	Mold compound	Phenol Resin (Proprietary)	Proprietary		31.004	mg	30018	23577
Encapsulation				supplier	Mold compound	Fused Silica (SiO2)	60676-86-0		913.997	mg	884931	695055
Encapsulation				supplier	Mold compound	Carbon Black	1333-86-4		5.167	mg	5003	3929
Encapsulation				supplier	Mold compound	Metal Hydroxide	Proprietary		51.674	mg	50031	39296
Wire	Other inorganic materials	2.520	mg	supplier	Wire	Gold (Au)	7440-57-5		2.495	mg	990079	1897
Wire				supplier	Wire	Palladium (Pd)	2023568		0.025	mg	9921	19
Finishing	Other inorganic materials	1.083	mg	supplier	Connection coating	Nickel (Ni)	7440-02-0		0.956	mg	882733	727
Finishing				supplier	Connection coating	Palladium (Pd)	7440-05-3		0.057	mg	52632	43
Finishing				supplier	Connection coating	Gold(Au)	7440-57-5		0.039	mg	36011	30
Finishing				supplier	Connection coating	Silver(Ag)	7440-22-4		0.031	mg	28624	24